

Listing of Claims:

Claim 1. (original) An epoxy resin composition for a printed wiring board, comprising an epoxy resin, a phenol novolac resin and a curing accelerator, characterized in that said epoxy resin comprises an epoxy (a) and an epoxy (b), wherein the epoxy (a) is a brominated epoxy resin, obtainable by reacting/mixing a bisphenol A epoxy resin with tetrabromobisphenol A, said brominated epoxy resin having an epoxy equivalent of 350 g/eq to 470 g/eq and containing an n=0 component in a ratio of 20% to 35% in terms of area percentage in a GPC chart; and the epoxy (b) is one or more of bifunctional epoxy resins, obtainable by reacting epichlorohydrin with any one selected from the group consisting of bisphenol A, bisphenol F and tetrabromobisphenol A, said bifunctional epoxy resins having an n=0 component in a content of 60% or higher in term of area percentage in a GPC chart; said epoxy (a) and epoxy (b) are contained in total in an amount of 80% to 100% by weight, preferably 93% to 100% by weight, based on the total weight of the epoxy resin; said epoxy (a) is contained in an amount of 75% to 97% by weight, based on the total weight of the epoxy resin; and said epoxy resin has a bromine content of 18% to 30% by weight, based on the total weight of the epoxy resin.

Claim 2. (original) An epoxy resin composition for a printed wiring board according to claim 1, characterized in that the phenol novolac resin is a phenol novolac resin, obtainable by reacting formaldehyde with one selected from the group consisting of phenol, cresol and bisphenol A; said phenol novolac resin containing a bifunctional component in an amount of 15% to 30%.

Claim 3. (currently amended) An epoxy resin composition for a printed wiring board according to claim 1-~~or 2~~, characterized in that an inorganic filler is contained.

Claim 4. (original) An epoxy resin composition for a printed wiring board described in claim 3, characterized in that a glass powder and/or silica filler is contained.

Claim 5. (currently amended) A prepreg for a printed wiring board, characterized in that the prepreg is obtainable by impregnating a glass cloth with a varnish comprising an organic solvent and an epoxy resin composition for a printed wiring board according to ~~any one of claims 1 to 4~~claim 1 and drying the vanish to B-stage.

Claim 6. (original) A laminated board for a printed wiring board, a printed wiring board or a laminated printed wiring board, characterized in that a prepreg for a printed wiring board according to claim 5 is used for the preparation thereof.

Claim 7. (new) An epoxy resin composition for a printed wiring board according to claim 2, characterized in that an inorganic filler is contained.

Claim 8. (new) A prepreg for a printed wiring board, characterized in that the prepreg is obtainable by impregnating a glass cloth with a varnish comprising an organic solvent and an epoxy resin composition for a printed wiring board according to claim 2 and drying the vanish to B-stage.

Claim 9. (new) A prepreg for a printed wiring board, characterized in that the prepreg is obtainable by impregnating a glass cloth with a varnish comprising an organic solvent and an epoxy resin composition for a printed wiring board according to claim 3 and drying the vanish to B-stage.

Claim 10. (new) A prepreg for a printed wiring board, characterized in that the prepreg is obtainable by impregnating a glass cloth with a varnish comprising an organic solvent and an epoxy resin composition for a printed wiring board according to claim 4 and drying the vanish to B-stage.

Respectfully submitted,

John F. Hoffman
Registration No. 26,280

Attorney for Applicant

JFH/pmp

BAKER & DANIELS
111 East Wayne Street, Suite 800
Fort Wayne, IN 46802

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